

<b>Notice of References Cited</b>	Application/Control No. 10/717,219	Applicant(s)/Patent Under Reexamination FARIS, SADEG M.	
	Examiner Tuan Quach	Art Unit 2814	Page 1 of 1

**U.S. PATENT DOCUMENTS**

*		Document Number Country Code-Number-Kind Code	Date MM-YYYY	Name	Classification
*	A	US-4,903,118	02-1990	Iwade, Shuhei	257/783
*	B	US-6,159,323	12-2000	Joly et al.	156/241
*	C	US-6,316,333	11-2001	Bruel et al.	438/458
*	D	US-6,342,433	01-2002	Ohmi et al.	438/455
*	E	US-6,355,501	03-2002	Fung et al.	438/107
*	F	US-6,777,312	08-2004	Yang et al.	438/464
	G	US-			
	H	US-			
	I	US-			
	J	US-			
	K	US-			
	L	US-			
	M	US-			

**FOREIGN PATENT DOCUMENTS**

*		Document Number Country Code-Number-Kind Code	Date MM-YYYY	Country	Name	Classification
	N					
	O					
	P					
	Q					
	R					
	S					
	T					

**NON-PATENT DOCUMENTS**

*		Include as applicable: Author, Title Date, Publisher, Edition or Volume, Pertinent Pages)
*	U	Gui, C., et al., Selective Wafer Bonding by Surface Roughness Control, Journal of the Electrochemical Society, Vol. 148, No. 4, April 2001, pp. G225-G228.
	V	
	W	
	X	

\*A copy of this reference is not being furnished with this Office action. (See MPEP § 707.05(a).)  
Dates in MM-YYYY format are publication dates. Classifications may be US or foreign.